

PARTIALLY FORMING AT LEAST ONE
HOLE IN A FIRST SIDE OF A
SUBSTRATE SUCH AS BY REMOVING
MATERIAL FROM THE SUBSTRATE TO
FORM AT LEAST ONE RECESS IN THE
FIRST SIDE

BONDING A WAFER TO THE SUBSTRATE TO OBTAIN A DEVICE SUBSTRATE

BONDING A CAPSULE TO THE DEVICE SUBSTRATE

THINNING THE SUBSTRATE DOWN BY REMOVING MATERIAL FROM THE SECOND SIDE OF THE SUBSTRATE SUCH AS BY ETCHING THE SUBSTRATE AT THE SECOND SIDE

FINISH FORMING THE AT LEAST ONE HOLE COMPLETELY THROUGH THE SUBSTRATE BETWEEN THE FIRST AND SECOND SIDES